

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4	((("3401126") or ("3429040")).PN.	USPAT; USOCR	OR	OFF	2008/04/30 09:40
L2	1	1 and (land or pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 09:42
L3	29	(solder\$3 adj ((pad or land) adj thickness))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 09:53
L4	0	((solder\$3 near5 ((pad or land) near5 thickness)) with (gap adj height))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 09:58
L5	0	((solder\$3 with ((pad or land) near5 thickness)) same (gap adj height))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 10:00
L6	1	((solder\$3 same ((pad or land) with thickness)) same (gap adj height))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 10:01
L7	1	((solder\$3 same ((pad or land) with thickness)) same (gap near5 height))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 10:01

L8	39	((pad or land) with thickness) same (gap near5 height))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 10:02
L9	1544	((chip or board or substrate) near5 ("opto-electronic" or (opto adj electronic)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 11:20
L10	230	((chip or board or substrate) adj ("opto-electronic" or (opto adj electronic)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 11:21
L11	0	((chip with board with substrate) adj ("opto-electronic" or (opto adj electronic)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 11:21
L12	0	((chip same board same substrate) adj ("opto-electronic" or (opto adj electronic)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 11:21
L13	0	((chip same (board same substrate)) adj ("opto-electronic" or (opto adj electronic)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 11:21
L14	0	((chip same (board and substrate)) adj ("opto-electronic" or (opto adj electronic)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 11:22

L15	0	((chip and (board and substrate)) adj ("opto-electronic" or (opto adj electronic)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 11:22
L16	2	((chip and board) adj ("opto-electronic" or (opto adj electronic)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 11:22

**4/30/2008 1:25:47 PM**

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